P0183 Drawing number #23550
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Author: B. Muhlfelder File: P0183A.DOC

P0183 Procedure for epoxying readout cable clip and short carrier to heater assy. and for epoxying grt to either a long or short carrier

Document Revision Record

Rev	Date	ECO #	Pages Affected	Description
A	3/22/99	966	all	revise procedure
-	3/5/99	NA	NA	new procedure

Note: This part is not ESD sensitive.

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Authority to Redline: B. Muhlfelder

Assembly procedure for 23550-101.

Materials & Supplies
1. heater assy 23529-101
2. clip, thermal ground, on-off 25145-101
3. carrier instrumentation, short 22737-101
4. adhesive tra-bond 2115

1. Preparation
1.1 Record serial number for heater to be used for pins #1 and #2 (heater 1): _____. Record serial number for heater to be used for pins #3 and #4(heater 2):_____. Record probe C connector ID_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.
1.3 Insert heater 1 into the carrier. Apply epoxy.
1.4 Insert heater 2 into the thermal on-off clip. Apply epoxy.
1.5 Apply drop of epoxy to back nut of lemo connector to prevent loosening of connector.
1.6 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag
2.1 Label bag with heater serial numbers and Probe C connector ID.

2.2 Place assembly into bag.

_____ _____
Operator date

_____ _____
QA date

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Assembly procedure for 23179-202

Materials & Supplies
1. grt sub-assy 23180-101
2. carrier short 22737-101
3. adhesive tra-bond 2115

1. Preparation
1.1 Record serial number for grt _____. Record probe C connector ID_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.
1.3 Insert grt into the carrier. Apply epoxy.
1.4 Apply drop of epoxy to back nut of lemo connector to prevent loosening of connector.
1.5 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag
2.1 Label bag with grt serial number and Probe C connector ID.
2.2 Place assembly into bag.

_____ _____
Operator date

_____ _____
QA date

Assembly procedure for 23179-203

Materials & Supplies
1. grt sub-assy 23180-102
2. carrier short 22737-101
3. adhesive tra-bond 2115

1. Preparation
1.1 Record serial number for grt _____. Record probe C connector ID_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.

1.3 Insert grt into the carrier. Apply epoxy.
1.4 Apply drop of epoxy to back nut of lemo connector to prevent loosening of connector.
1.5 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag

2.1 Label bag with grt serial number and Probe C connector ID.
2.2 Place assembly into bag.

_____ _____
Operator date

Assembly procedure for 23179-201

Materials & Supplies

1. grt sub-assy 23180-101
2. carrier long 22399-201
3. adhesive tra-bond 2115

1. Preparation

1.1 Record serial number for grt _____. Record probe C connector ID_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.
1.3 Insert grt into the carrier. Apply epoxy.
1.4 Apply drop of epoxy to back nut of lemo connector to prevent loosening of connector.
1.5 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag

2.1 Label bag with grt serial number and Probe C connector ID.

2.2 Place assembly into bag.

_____ _____
Operator date

_____ _____
QA date

Assembly procedure for 23532-103.

Materials & Supplies

1. SD sub-assy 25601-102
2. Carrier 22737-101
3. Epoxy, Tra bond 2115

1. Preparation

1.1 Record serial number for SD: _____. Record probe C connector IDs_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.
1.3 Place SD inside of carrier. Apply epoxy.

1.4 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag
2.1 Label bag with SD serial number and Probe C connector IDs.

2.2 Place assembly into bag.

_____ _____
Operator date

_____ _____
QA date

Assembly procedure for 23532-101.

Materials & Supplies
1. SD sub-assy 25601-101
2. Carrier 22399-201, 2 ea.
3. Epoxy, Tra bond 2115

1. Preparation
1.1 Record serial number for SD #1: _____. Record serial number for SD#2:_____. Record probe C connector ID_____.

____ _____
RE date

1.2 Prepare trabond epoxy by mixing the 2 halves of the packet together.
1.3 Place SDs inside of carriers. Apply epoxy.
1.4 Wait a minimum of 12 hours for the epoxy to cure.

_____ ____
Operator date

2. Bag and Tag
2.1 Label bag with SD serial numbers and Probe C connector IDs.

2.2 Place assembly into bag.

_____ _____
Operator date

_____ _____
QA date